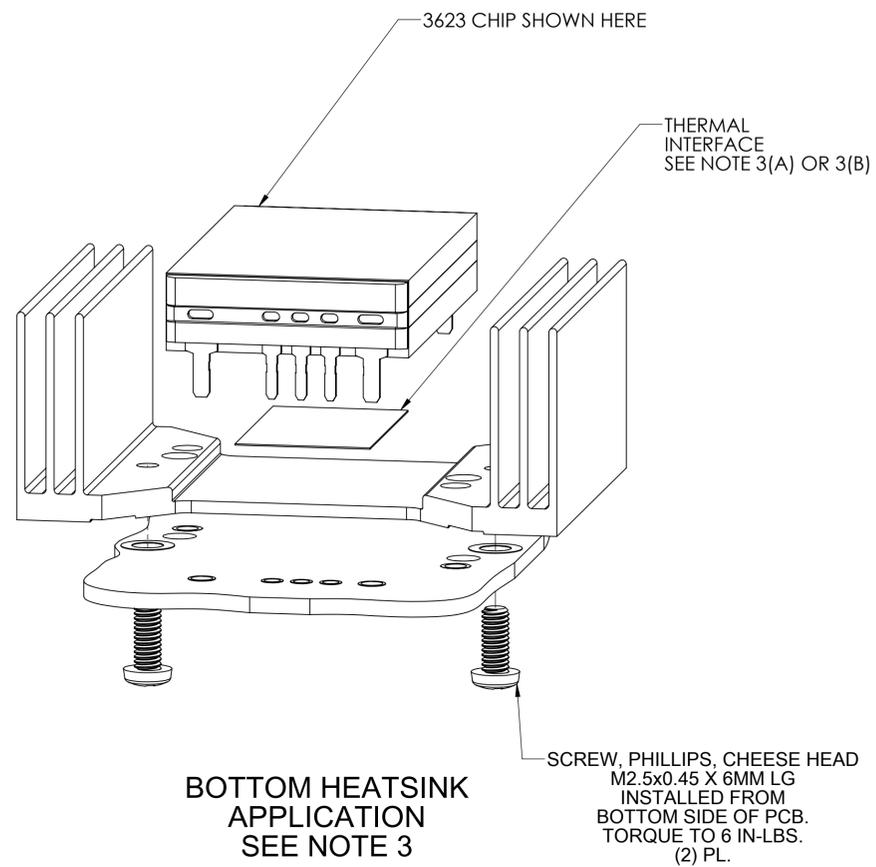
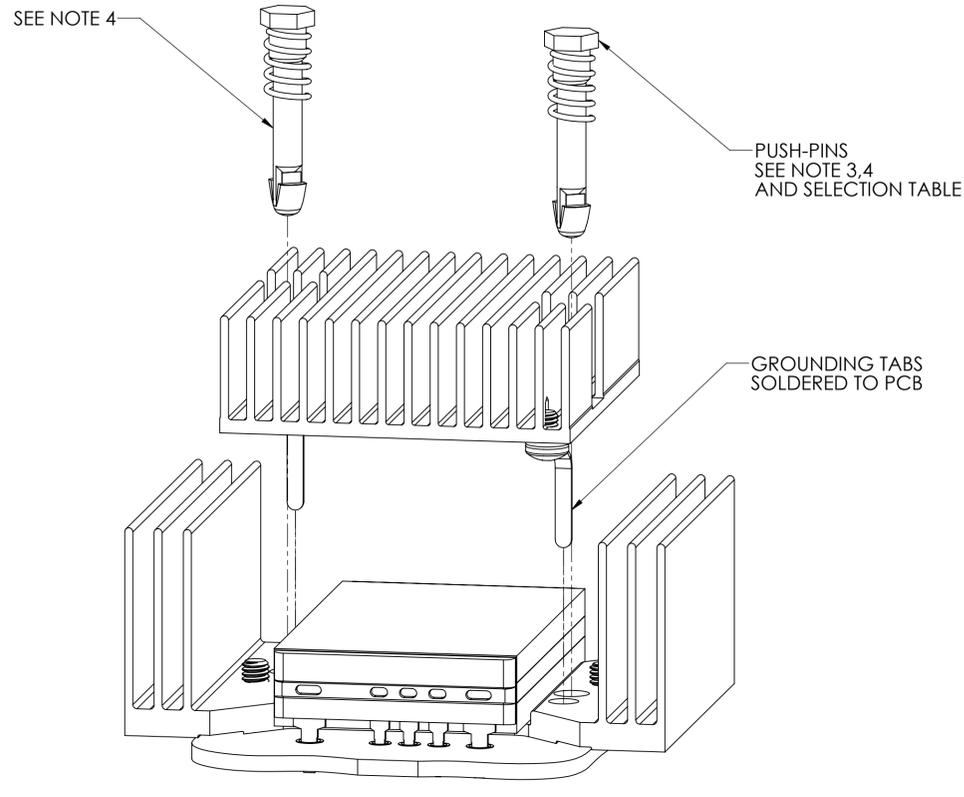


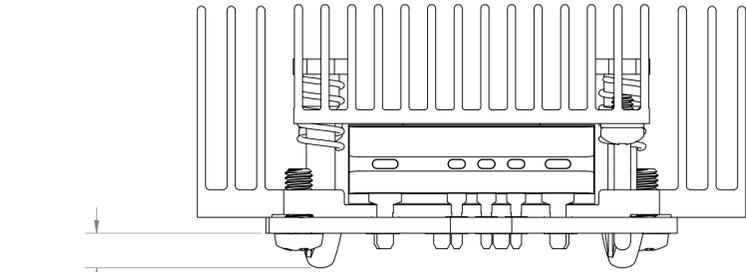
REV.	DESCRIPTION	INTL	DATE	APVD
1	RELEASED PER E141039	SJW	09/03/14	RH
2	REVISED PER E200529	DKT	10/19/20	RLT



**BOTTOM HEATSINK APPLICATION
SEE NOTE 3**



**TOP HEATSINK APPLICATION
SEE NOTE 3**



ASSEMBLED FRONT VIEW

NOTES:

- FOR PCB LAYOUT SEE VICOR APPLICATION DRAWING 40438.
- ROHS COMPLIANT PER CST-0001 LATEST REVISION.
-
- THE SOLDERING METHOD USED FOR CHIPS (AND OPTIONAL HEATSINK GROUNDING) IS IMPORTANT WHEN SELECTING A THERMAL INTERFACE MATERIAL (TIM). THE PHASE-CHANGE TIM SHOWN IN THESE ILLUSTRATIONS MAY BE DAMAGED BY TEMPERATURES OVER 125C, SO TWO ASSEMBLY PROCEDURES ARE DESCRIBED BELOW:
(A) FOR HAND-SOLDERING ONLY,
(B) FOR WAVE-SOLDERING AND/OR HAND-SOLDERING.

(A) PLACE BOTTOM-SIDE HEATSINK (WITH PRE-ATTACHED PHASE-CHANGE TIM) ON PCB. PLACE CHIP AND TOP-SIDE HEATSINK (WITH PRE-ATTACHED TIM AND GROUNDING TABS). WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH BOTH HEATSINKS AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.) IMPORTANT: TO SET FINAL THICKNESS OF PHASE-CHANGE TIM ENSURE THAT THE ENTIRE ASSEMBLY IS RAISED ABOVE 65C FOR SEVERAL MINUTES. HAND-SOLDER ALL CHIP AND GROUNDING PINS. ADDITIONAL SOLDERING IRON HEAT MAY BE REQUIRED TO COMPENSATE FOR LOSSES TO THE HEATSINKS.

(B) WAVE SOLDERING TEMPERATURES ARE UNSUITABLE FOR PLASTIC PUSH-PINS AND PHASE-CHANGE TIM, SO PARKER CHOMERICS GEL8010 IS RECOMMENDED AS A TIM. APPLY A UNIFORM .003" (.076MM) LAYER OF TIM TO THE TOP AND BOTTOM SURFACE OF THE CHIP, OR TO THE CORRESPONDING HEATSINK SURFACES. PLACE BOTTOM-SIDE HEATSINK, CHIP, AND TOP-SIDE HEATSINK ON PCB. WITH A CUSTOM FIXTURE APPLY APPROX. 10 LBS LOAD TO THE TOP-SIDE HEATSINK AND THEN WAVE-SOLDER ALL PINS. REMOVE FIXTURE AND INSERT PLASTIC PUSH-PINS THROUGH BOTH HEATSINKS AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.)

- CARE SHOULD BE TAKEN TO AVOID FULLY COMPRESSING THE PUSH-PIN SPRING DURING INSTALLATION AS THIS WOULD EXPOSE THE CHIP TO FORCES GREATER THAN THE RECOMMENDED LIMIT OF 3.1 LBF (13.8 N) PER PUSH-PIN.

	HEATSINK TYPE	P/N HEATSINK, TIM AND GROUND TAB	P/N HEATSINK W/GROUND TAB ONLY
SOLDERING METHOD (SEE NOTE 2)	-	2(A) HAND SOLDER ONLY	2(B) WITH VICOR 40325 THERMAL GEL
3623	DUAL 11MM	40518	40526
	DUAL 19MM	TBD	TBD

HEATSINK SELECTION

PUSH-PINS W/ SPRINGS (100/BAG)	COLOR	PCB THK NOMINAL RANGE	PCB THK MINIMUM	PCB THK MAXIMUM
32436	BLUE	1.143 MM TO 1.854 MM [.045"] TO [.073"]	1.041 MM [.041"]	2.057 MM [.081"]
32437	GRAY	1.880 MM TO 2.438 MM [.074"] TO [.096"]	1.676 MM [.066"]	2.692 MM [.106"]

PUSH-PIN SELECTION

DRAWN BY Robert Wasik	DATE 09/06/2013	VICOR swd	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE: INCH / (MM)		ASSY DWG DUAL HEATSINK 3623	
TOLERANCES ARE: DECIMALS ANGLES X.XX (X.X) = +0.01 (0.25) ±1° X.XXX (X.XX) = ±0.005 (0.127)			
THIRD ANGLE PROJECTION	SIZE D	CAGE CODE 67131	DWG NO 40190
DO NOT SCALE DRAWING	SCALE 3:1	REV 2	SHEET 1 OF 1